

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	214	((SIOC or SION or ARC or TERA)with (Oxygen near plasma))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/04 21:43
L2	58	((SIOC or SION or ARC or TERA)with (Oxygen near plasma))and (flow\$4 near rate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/04 21:44
L3	43	((SIOC or SION or ARC or TERA)with (Oxygen near plasma))and (oxygen with (sccm or (flow\$4 near rate)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/04 21:45
S1	0	10/702049	USPAT	OR	OFF	2007/09/17 16:19
S2	2	10/702049	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 12:50
S4	72	"6316167"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:08
S5	7252	((430/313/) or (430/272.1/) or (430/311/) or (427/569/) or (427/282/) or (427/535/)). CCLS	USPAT; USOCR	OR	OFF	2007/09/18 17:09
S7	3	S5 and TERA	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:11
S8	1666	S5 and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:11
S9	0	S5 and deposit and etch and R:C:H:X	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:12

S10	0	S5 and deposit and R:C:H:X	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:12
S11	0	S5 and deposit and R:C:O:X	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:12
S12	2	S5 and R:C:O:X	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:13
S13	2	S5 and RCHX	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:14
S14	37	RCHX	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:14
S15	5	RCHX and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:14
S16	0	RCHX and deposit and HZ	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:09
S17	5	RCHX and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:16
S18	2	"20040178169"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/21 21:18
S19	0	RCHX and HZ and watt	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:09

S20	2	RCHX and HZ	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:10
S21	4	"6903023"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:12
S22	2	"20070037100"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:15
S23	2	"20060049139"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:16
S24	2	"20040000534"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:26
S25	4	"1905170"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:27
S26	0	"19901905170"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:27
S27	121	"4905170"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:28
S28	82	"4905170"	USPAT; USOCR	OR	OFF	2007/09/19 12:31
S29	1	2002/0076843	USPAT; USOCR	OR	OFF	2007/09/19 12:32
S30	1	2002/0076843	USPAT; USOCR	OR	OFF	2007/09/19 12:33
S31	6	"6287959"	USPAT; USOCR	OR	OFF	2007/09/19 12:36
S32	20	"6380611"	USPAT; USOCR	OR	OFF	2007/09/19 12:41
S33	439343	(ARC or (anti near reflect\$3 near coat\$4)) deposit and rate and time	USPAT; USOCR	OR	OFF	2007/09/19 12:43

S34	110	(ARC or (anti near reflect\$3 near coat\$4)) with deposit with rate	USPAT; USOCR	OR	OFF	2007/09/19 12:44
S35	1	(anti near reflect\$3 near coat\$4) with deposit with rate	USPAT; USOCR	OR	OFF	2007/09/19 12:47
S36	8249	tetramethylcyclotetrasilicate or tetraethylorthosilicate or dimethyldimethoxysilane or octamethylcyclotetrasiloxane	USPAT; USOCR	OR	OFF	2007/09/19 12:50
S37	13879	tetramethylcyclotetrasilicate or tetraethylorthosilicate or dimethyldimethoxysilane or octamethylcyclotetrasiloxane	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 13:20
S38	1405	S37 and deposit and etch	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 12:52
S39	0	"l0" and (deposit near ratea)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 12:52
S40	0	"l0" and (deposit near rate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 12:52
S41	0	"l0" and (deposit near rate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 12:52
S42	1	"llo" and (deposit near rate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 12:53
S43	95	"llo" and ((inert near gas) or nitrogen or argon)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 12:54
S44	2	"10662022"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 13:11

S45	4	"7030468"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 13:21
S46	2	"10377061"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 17:09
S47	1	11/023815	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 17:10
S48	1	11/023815	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 17:10
S49	4	"7097779"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/21 21:26
S50	0	"SiOH" with etch with "DC" with bias	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/21 21:27
S51	1	"RCHX" with etch with "DC" with bias	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/24 17:44
S52	1	11/801058	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/24 17:45
S53	50	"6316167"	USPAT	OR	OFF	2007/10/03 15:21
S54	50	"6316167"	USPAT	OR	OFF	2007/10/03 15:23
S55	53	etch and SiOH and hydrogen	USPAT	OR	OFF	2007/10/03 15:23
S56	166	etch and SiOH and hydrogen	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/03 15:23

S57	202	etch with SiCH with hydrogen	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/03 15:23
S58	0	etch with SiCH with hydrogen	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/03 15:23
S59	6	etch same SiCH same hydrogen	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/03 15:25
S60	0	etch same SiCH same hydrogen and socm	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/03 15:25
S61	6	etch same SiCH same hydrogen and rate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/03 15:27
S62	6	"7183201"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/03 15:30
S63	4	09/912103	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/03 15:30
S64	1	"7030008"	USPAT	OR	OFF	2007/10/04 10:24
S65	0	"20050100683"	USPAT	OR	OFF	2007/10/04 10:25
S66	1	"20050100683"	US-PGPUB; USPAT	OR	OFF	2007/10/04 11:09
S67	45	"6063233"	US-PGPUB; USPAT	OR	OFF	2007/10/04 11:34
S68	17	plasma and deposition and SiCOH and shower and temperature	US-PGPUB; USPAT	OR	OFF	2007/10/04 11:35
S69	17	plasma and deposition and SiCOH and shower and temperature	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 11:35

S70	18	plasma and deposit\$4 and SICOH and shower and temperature	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 11:36
S71	6	plasma and deposit\$4 and SICOH and (shower with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 11:46
S72	0	((plasma with deposit\$4 with SICOH)and (post near process)and ((de near chuck) or remove or lift)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 11:47
S73	0	((plasma same deposit\$4 same SICOH)and (post near process)and ((de near chuck) or remove or lift)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 11:48
S74	4	((plasma and deposit\$4 and SICOH)and (post near process)and ((de near chuck) or remove or lift)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 12:16
S75	15	plasma and deposit\$4 and (TERA or SICOH or organosilicate)and(post near process)and ((de near chuck) or remove or lift)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 12:26
S76	15	plasma and deposit\$4 and (TERA or SICOH or SIOH or organosilicate)and(post near process)and((de near chuck) or remove or lift)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 12:30
S77	7	2002-194431	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 12:35
S78	24	"6380611"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 12:36
S79	7	"6287959"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 12:39

S80	2	"20020076843"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 12:45
S81	57	SiCOH and deposit and plasma and (tetramethylcyclotetrasilane or tetraethylorthosilicate or dimethyldimethoxysilane or octamethylcyclotetrasiloxane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 12:47
S82	24	SiCOH with deposit with plasma with (tetramethylcyclotetrasilane or tetraethylorthosilicate or dimethyldimethoxysilane or octamethylcyclotetrasiloxane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 13:06
S83	0	SiCOH with deposit with plasma with (tetramethylcyclotetrasilane or tetraethylorthosilicate or dimethyldimethoxysilane or octamethylcyclotetrasiloxane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 13:06
S84	0	SiCOH same deposit same plasma same (tetramethylcyclotetrasilane or tetraethylorthosilicate or dimethyldimethoxysilane or octamethylcyclotetrasiloxane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 13:06
S85	0	SiCOH same deposit same plasma same (tetramethylcyclotetrasilane or tetraethylorthosilicate or dimethyldimethoxysilane or octamethylcyclotetrasiloxane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 13:06
S86	57	SiCOH and deposit and plasma and (tetramethylcyclotetrasilane or tetraethylorthosilicate or dimethyldimethoxysilane or octamethylcyclotetrasiloxane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 13:07
S87	75	(SiCOH with deposit\$4) and plasma and (tetramethylcyclotetrasilane or tetraethylorthosilicate or dimethyldimethoxysilane or octamethylcyclotetrasiloxane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 13:22
S88	72	"6316167"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 02:47
S89	3	"20030017694"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 03:08

S90	72	"6316167"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 03:40
S91	33	"6436808"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 03:40
S92	2	deposit and chamber and (SCO) and (shower with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 03:46
S93	19466105	US "6764951" B1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 03:44
S94	4	"6764951"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 03:45
S95	6	(SCO) and (shower with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 05:36
S96	5	(SCO) and (shower with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 03:51
S97	6	organosilicon and (shower with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 03:52
S98	19	"885985"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 04:26
S99	2	"20030003768"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 04:26

S100	2	("SOOH" or organosilicate)and (shower with temperature)and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 05:37
S101	2	("SOOH" or organosilicate)and (shower with temperature)and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:17
S102	16	"638803"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 05:40
S103	21	("SOOH" or organosilicate)and (wall with temperature)and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 05:53
S104	9	"938435"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 05:53
S105	2	("SOOH" or organosilicate)and (shower with (temperature or centigrade))and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:24
S106	16	"638803"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:22
S107	331	(shower with (temperature or centigrade))and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:24
S108	180	(shower with (temperature or centigrade))and deposit and uniform	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:24
S109	3	(shower with (temperature or centigrade))with deposit with uniform	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:28

S110	21	((shower with (temperature or centigrade) with deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:43
S111	0	((de near chuck\$3) with substrate or wafer)with while with plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:47
S112	0	((de near chuck\$3) with substrate or wafer)with while with deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:47
S113	0	((de near chuck\$3) with substrate or wafer)same while same deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:47
S114	0	((de near chuck\$3) same substrate or wafer)same while same deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:47
S115	0	((de near chuck\$3) and (substrate or wafer) and while and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:48
S116	0	((de near chuck\$3)with (substrate or wafer)))and while and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:53
S117	77	((de near chuck\$3)with (substrate or wafer))) and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 07:00
S118	1	((de adj chuck\$3)with (substrate or wafer))) with deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 07:00
S119	1	((de adj chuck\$3)with (substrate or wafer))) same deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 07:00

S120	1	(((de adj chuck\$3) same (substrate or wafer))) same deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 07:00
S121	77	(((de adj chuck\$3) same (substrate or wafer))) and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 07:01
S122	76	(((de adj chuck\$3) same (substrate or wafer))) and deposit and (during or while or after or before)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 07:12
S123	5440	(((lift\$3) with (substrate or wafer))) and deposit and (during or while or after or before)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 07:12
S124	71	(((lift\$3) with (substrate or wafer))) with deposit with (during or while or after or before)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 07:13
S125	71	(((lift\$3) with (substrate or wafer))) with deposit with (during or while or after or before)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 07:13
S126	2	"5466524"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/15 18:42
S127	1	"10546736"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/15 18:43
S128	1	"10546736"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/15 18:44
S129	1	10/534401	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/15 18:44

S130	64	plasma and (de near chuck)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/24 19:17
S131	6	"6452775"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 11:25
S132	0	(de near chuck) and (plasma near deposit \$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 11:25
S133	1	(de near chuck) and (plasma near deposit \$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 11:28
S134	39	(de near chuck) and (plasma with deposit \$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 11:28
S135	2	"20050100683"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 11:57
S136	2	"20050100683"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 11:58
S137	1	((de near chuck or " de-chuck") with (plasma near(coat\$4 or deposit)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 12:00
S138	1	((de near chuck or " de-chuck") same (plasma near(coat\$4 or deposit)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 12:00
S139	1	((de near chuck or " de-chuck") and (plasma near(coat\$4 or deposit)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 12:00

S140	25	((de near chuck or " de-chuck") and (plasma same(coat\$4 or deposit)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 13:40
S141	6	"2006004506"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 13:29
S142	13	"931272"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 13:29
S143	64	((de near chuck or " de-chuck") and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:26
S144	2	"20040137169"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:33
S145	0	((before with (substrate or wafer)) with lift) and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:34
S146	0	((before same (substrate or wafer)) with lift) and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:34
S147	0	((before same (substrate or wafer)) with lift\$4) and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:34
S148	0	((before same (substrate or wafer)) same lift\$4) and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:35
S149	2940	((before same (substrate or wafer)) same lift\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:35

S150	957	((before same (substrate or wafer)) same lft\$4)and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:35
S151	2940	((before same (substrate or wafer)) same lft\$4)sameplasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:35
S152	223	((before same (substrate or wafer)) same lft\$4)same plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:35
S153	34	((before same (substrate or wafer)) same lft\$4)with plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:37
S154	21	((before same (substrate or wafer)) with lft\$4)with plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 15:39
S155	2	"20060011224"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 15:41
S156	13	"682054"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 15:41
S157	21	"623445"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 18:00
S158	5753	(plasma antenna with coil)with switch	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 18:44
S159	2137	(plasma antenna with coil)with switch and coil	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 18:43
S160	205957	((("118") or ("156") or ("343")).CLAS.	USPAT; USOCR	OR	OFF	2007/10/26 18:43

S161	11	((plasma and antenna and coil) and switch). clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 18:44
S162	2	"20030003768"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 21:39
S163	700	"4951601"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 22:43
S164	13	((plasma near (deposit or process)) and (lift with (while or during) with (wafer or substrate) with plasma)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 23:00
S165	33	((plasma near (deposit or process)) and ((de near chuck)or (de-chuck) or (de near clamp)with (before or after) with (wafer or substrate) with plasma)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 23:15
S166	33	((plasma near (deposit or process)) and ((de near chuck)or (de-chuck) or (de near clamp)with (before) with (wafer or substrate) with plasma)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 23:15
S167	33	((plasma near (deposit or process)) and ((de near chuck)or (de-chuck) or (de near clamp)with (wafer or substrate)with (before near\$2 plasma))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 23:22
S168	9	((plasma near (deposit or process)) and (turn near off) with (RF or voltage or power) with (substarte or wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 23:26
S169	35	"478315"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:14
S170	75	((de near chuck) or (de near clamp)) and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:15

SI71	75	((de near chuck) or (de near clamp)) and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:15
SI72	1	((de near chuck) or (de near clamp)) and (plasma near deposit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:15
SI73	33	((de near chuck) or (de near clamp)) and (plasma and deposit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:16
SI74	57341	((de near chuck) or (de near clamp))with before or after and (plasma and deposit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:16
SI75	4	((de near chuck) or (de near clamp))with (before or after)) and (plasma and deposit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:18
SI76	0	((de near chuck) or (de near clamp))with (turn near off)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:43
SI77	1	(plasma with deposit) and ((DC near voltage) with bias with (electrostatic near chuck))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:47
SI78	72	"6316167"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:47
SI79	56	trouiller.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/04 12:53
SI80	1	SI79 and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/04 12:54

SI81	19	SI79 and resist\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/04 12:54
SI82	48	yorick.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/04 12:57
SI83	6	SI79 and SI82	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/04 12:58
SI84	2	10/702049	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/04 13:01
SI85	2	10/847891	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/04 13:03
SI86	2	10/750348	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/04 13:07
SI87	8	"6713386"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/04 13:08
SI88	81	"6316167"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/04 13:54
SI89	4	11/112880	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/04 15:44
SI90	2	"20030216009"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/04 15:53

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